

A

B

C

D

E

F

A

B

C

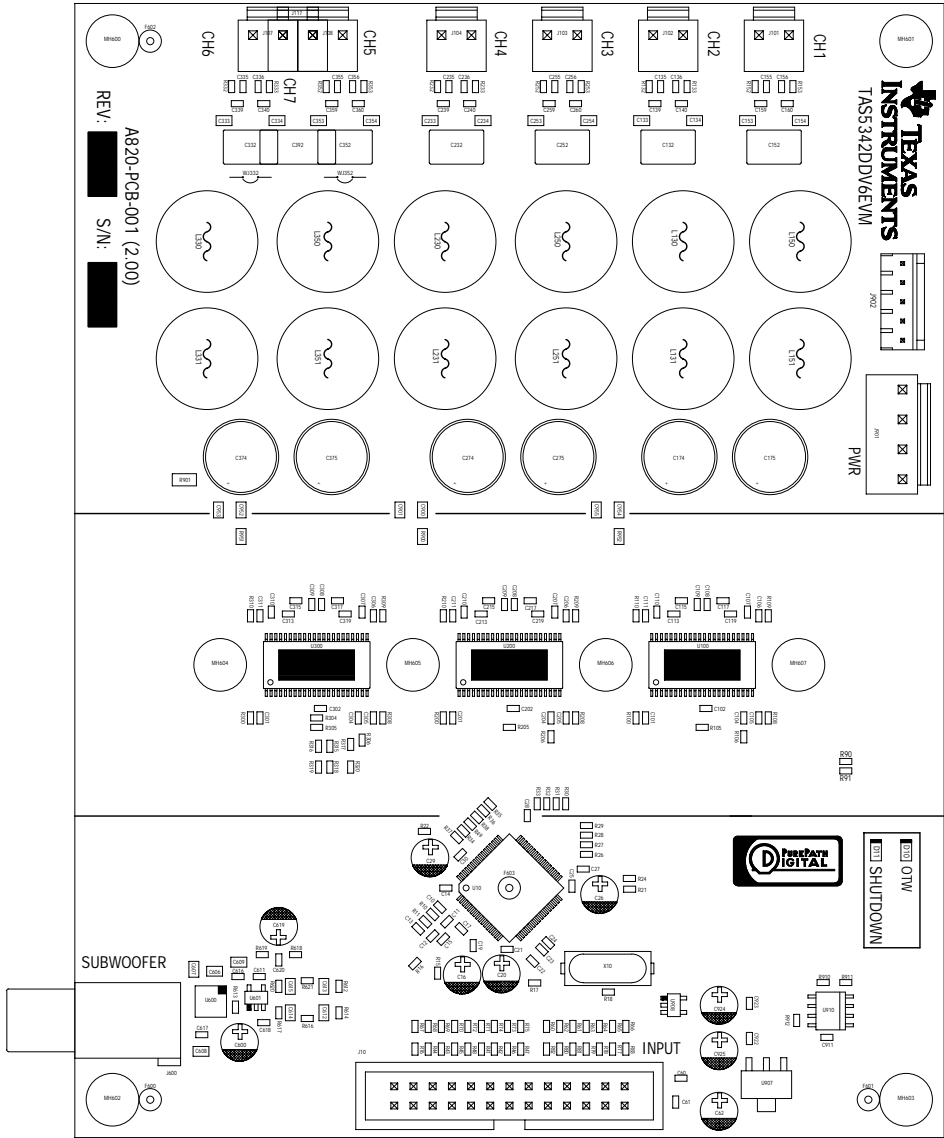
D

E

F

NOTES: UNLESS OTHERWISE SPECIFIED.

1. COMPONENT MOUNTING TYPES TOP/BOTTOM : SMD-Leaded / none.
2. X,Y COORDINATES AND ROTATION PROVIDED IN DATA FILES.
3. SOLDERING METHODS TYPE TOPSIDE : RES
4. SOLDERING METHODS TYPE BOTSIDE : RES / WAS
WAS - Wave soldering
RES - Reflow soldering
IRS - Infrared soldering
MHS - Manual hand-soldering
5. PCBLAYOUT BY GHDSIGN DENMARK. (+45)44441482
6. PCB CONTAINS BGA AND NSMD LEADLESS PACKAGES.



RevNo	Revision note	Date	Signature	Checked
2	Minor changes to placement, some new components.	2007/NOV/14	CMS	CMS

A3	Texas Instruments Lyngby Hovedgade 4, DK-2800 Lyngby		PCB No.	A820-PCB-001-2	
			Engineer	Jonas L. Holm	
Designed by KR/CMS		Checked by CMS	Approved by Jonas L. Holm	Date 2007/NOV/14	Scale 100 %
ASSY DRAWING			TAS5342DDV6EVM		
			A820-PCB-001	Rev 2	Sheet 1 OF 1